

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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HAKSOO HAN	11/02/2018
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16097026
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DATE SIGNED:	11/02/2018
Total Attachments: 2	
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source=G1035-13501-Assignment#page2.tif	

ASSIGNMENT

WHEREAS, I, **Haksoo HAN** have invented certain new and useful improvements in and to the invention entitled:

**NANOPOROUS MICRO-SPHERICAL POLYIMIDE
AEROGELS AND METHOD FOR PREPARING SAME**

described in an application for Letters Patent filed on October 26, 2018, and accorded U.S. Patent Application No. 16/097,026, which is a U.S. national phase application of International Patent Application No. PCT/KR2014/008940, filed on September 25, 2014, (hereinafter collectively the "Invention").

AND, WHEREAS, **INDUSTRY-ACADEMIC COOPERATION FOUNDATION, YONSEI UNIVERSITY**, a South Korean university, whose address is 50, Yonsei-ro, Seodaemun-gu, Seoul, 03722, Republic of Korea (hereinafter "ASSIGNEE"), is desirous of acquiring certain rights in the Invention including all patents and patent applications thereto;

NOW, THEREFORE, in view of good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, my entire right, title and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto in and to said Invention including said United States patent application(s), any other United States patent application(s), including provisional, divisional, renewal, substitute, continuation, continuation-in-part, reexamination and reissue applications, and extensions thereof based in whole or in part on said United States patent application or in whole or in part on said Invention, any foreign applications, including international and regional applications, based in whole or in part on any of the aforesaid United States applications or in whole or in part on said Invention, in and to any and all letters patent, including extensions thereof, of any country which have been or may be granted on any of the aforesaid applications or on said Invention or any part(s) thereof, and in and to any right to claim priority to any of the aforesaid patents and/or patent applications;

AND I hereby authorize and request, Duane Morris LLP, whose address is 1875 NW Corporate Blvd., Suite 300, Boca Raton, Florida 33431-8561 to insert hereon any identification

necessary or desirable for recordation of this document, including the filing date and application number of said application when known.

AND I hereby agree for myself and my heirs, executors and administrators to execute without further consideration any further documents and instruments which may be necessary, lawful and proper in the prosecution of said above-referenced application or in the preparation or prosecution of any continuing, substitute, divisional, renewal, reexamination or reissue application or in any amendments, extensions or interference proceedings, or other applications for patents of any region or country, that may be necessary to secure to ASSIGNEE its interest and title in and to said Invention or any part(s) thereof, and in and to said several patents or any of them;

AND I hereby covenant for myself and my legal representatives, and agree with said ASSIGNEE, its successors and assigns, that I have granted no right or license to make, use, sell or offer to sell said Invention, to anyone except said ASSIGNEE, that prior to the execution of this deed, my right, title and interest in said Invention had not been otherwise encumbered, and that I have not and will not execute any instrument in conflict therewith;

AND I do hereby authorize and request the United States Commissioner for Patents to issue any and all letters patent which may be granted upon said United States applications, or upon said Invention or any part(s) thereof when granted, to said ASSIGNEE;

IN WITNESS WHEREOF, I have hereunto set my hand and seal.

FOR ASSIGNOR: The Named Inventor

Date NOV 2, 2018

Inventor


Haksoo HAN